Precision Voltage Regulator

Description

This monolithic voltage regulator is designed for use with either positive or negative supplies as a series, shunt, switching, or floating regulator with currents up to 150 mA. Higher current requirements may be accommodated through the use of external NPN or PNP power transistors. This device consists of a temperature compensated reference amplifier, error amplifier, power series pass transistor, current limit, and remote shutdown circuitry.

The SG723 will operate over the full military ambient temperature range of -55°C to 125°C.

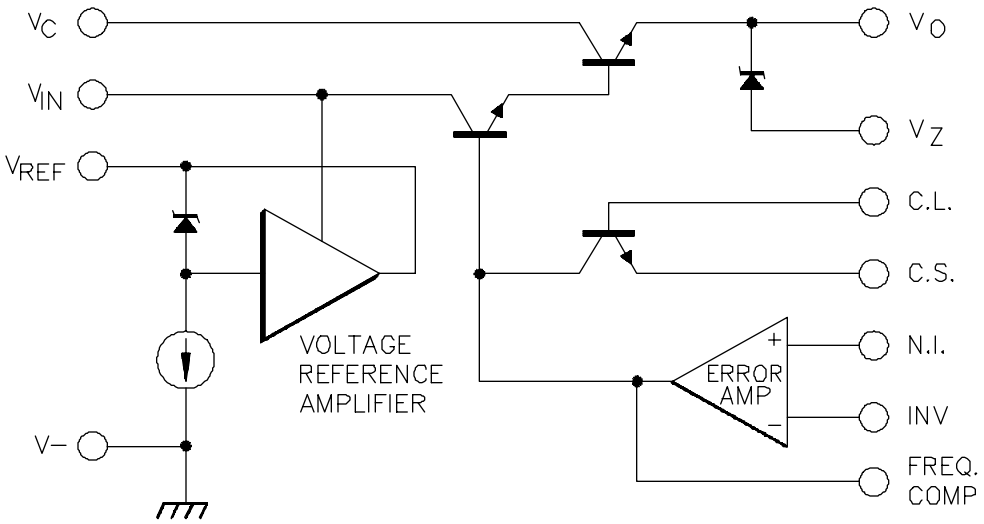
Features

- Positive or Negative Supply Operation
- Series, Shunt, Switching or Floating Operation
- Low Line and Load Regulation
- Output Adjustable from 2 V to 37 V
- Output Current to 150 mA
- Low Standby Current Drain
- 0.002%/°C Average Temperature Variation

High Reliability Features

- MIL-M38510/10201BHA - SG723F-JAN
- MIL-M38510/10201BIA - SG723T-JAN
- MIL-M38510/10201BCA - SG723J-JAN
- MSC-AMS Level "S" Processing Available

Block Diagram



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Absolute Maximum Ratings (Note 1)

Pulse (50 ms) Input Voltage from V_{IN} to V- ..... 50 V
Continuous Input Voltage from V_{IN} to V- ..... 40 V
Input to Output Voltage Differential ..... 40 V
Maximum Output Current ..... 150 mA
Current from V_Z (J-Package only)..... 25 mA

Note 1. Exceeding these ratings could cause damage to the device.

Current from V_{REF}.....15 mA
Operating Junction Temperature
Hermetic (T, J, F - Packages)..... 150°C
Storage Temperature Range ..... -65°C to 150°C
Lead Temperature (Soldering, 10 s)..... 300°C

Thermal Data

J Package:
Thermal Resistance-Junction to Case, θ_{JC}..... 30°C/W
Thermal Resistance-Junction to Ambient, θ_{JA} ..... 80°C/W
T Package:
Thermal Resistance-Junction to Case, θ_{JC}..... 25°C/W
Thermal Resistance-Junction to Ambient, θ_{JA} ..... 130°C/W
F Package:
Thermal Resistance-Junction to Case, θ_{JC}..... 80°C/W
Thermal Resistance-Junction to Ambient, θ_{JA} ..... 145°C/W

Note A. Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

Note B. The above numbers for θ_{JC} are maximums for the limiting thermal resistance of the package in a standard mounting configuration. The θ_{JA} numbers are meant to be guidelines for the thermal performance of the device/ pc- board system. All of the above assume no ambient airflow.

Recommended Operating Conditions (Note 2)

Input Voltage Range ..... (V_{OUT} +4.5 V) to 38 V
Output Current Range ..... 5 mA to 45 mA
Reference Current..... 5 mA

Note 2. Range over which the device is functional.

Zener Current (J-Package only)..... 5 mA
Operating Ambient Temperature Range
SG723 ..... -55°C to 125°C

Electrical Characteristics

(Unless otherwise specified, these specifications apply for the operating ambient temperature of T_A = 25°C, V_{IN} = V_C = 12 V, V- = 0 V, V_{OUT} = 5 V, I_L = 1 mA, R_{SC} = 0 Ω, C_1 = 100 pF, and divider impedance as seen by error amplifier ≤ 10 kΩ. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)

Parameter	Test Conditions	SG723			Units
		Min.	Typ.	Max.	
Input Voltage Range		9.5		40	V
Output Voltage Range		2.0		37	V
Input to Output Differential		3.0		38	V
Line Regulation (Note 3)	V_{IN} = 12 V to 15 V		0.01	0.1	$\%V_{OUT}$
	$T_A = T_{MIN}$ to T_{MAX}			0.3	$\%V_{OUT}$
	V_{IN} = 12 V to 40 V		0.02	0.2	$\%V_{OUT}$
Load Regulation (Note 3)	I_L = 1 to 50 mA		0.03	0.15	$\%V_{OUT}$
	$T_A = T_{MIN}$ to T_{MAX}			0.6	$\%V_{OUT}$
Ripple Rejection	f = 50 Hz to 10 kHz				
	C_{REF} = 0		74		dB
	C_{REF} = 5 µF		86		dB
Temperature Stability (Note 4)	$T_A = T_{MIN}$ to T_{MAX}		0.002	0.015	%/°C
Short Circuit Current Limit	R_{SC} = 10 Ω		65		mA
Reference Voltage		6.95	7.15	7.35	V
Output Noise Voltage	BW = 100 Hz to 10 kHz				
	C_{REF} = 0		20		μV_{rms}
	C_{REF} = 5 µF		2.5		μV_{rms}
Standby Current Drain	I_L = 0, V_{IN} = 30 V		2.3	3.5	mA
Long Term Stability			0.1		%/khr

Note 3. Applies for constant junction temperature. Temperature drift effects must be taken into account separately when the unit is operating under conditions of high dissipation.

Note 4. These parameters, although guaranteed, are not tested in production.

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Characteristic Curves

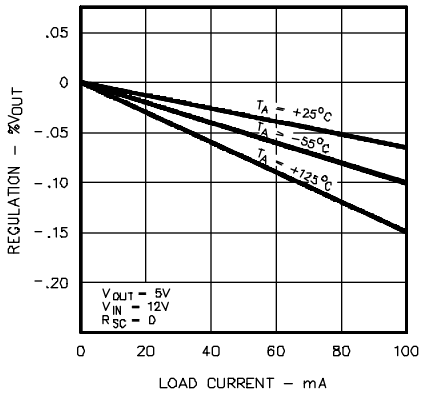

Figure 1. Load Regulation

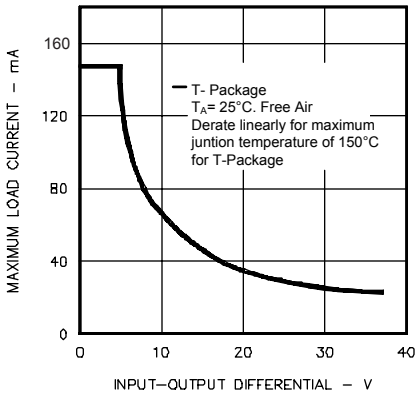

Figure 2. Maximum Load Current

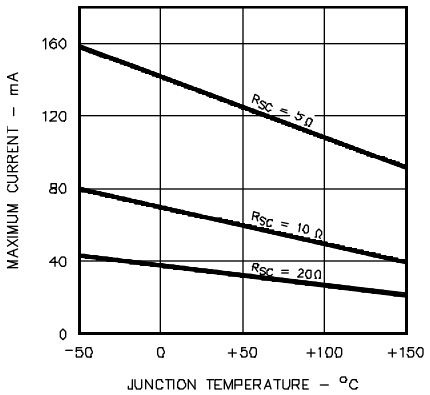

Figure 3. Current Limiting Characteristics

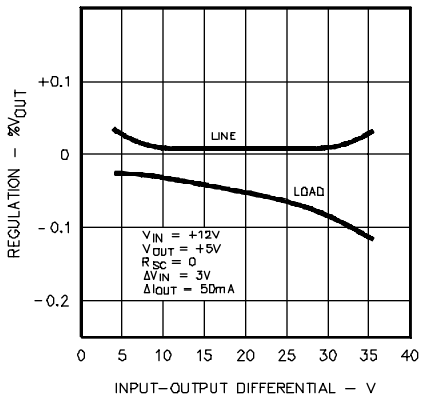

Figure 4. Regulations vs. Input-Output Voltage Regulation

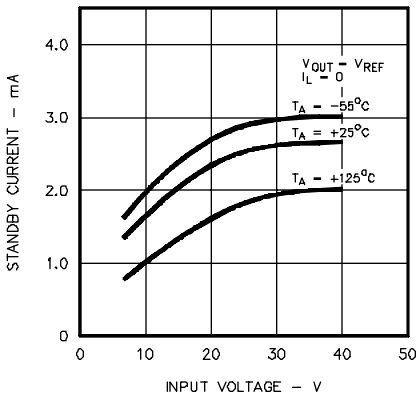

Figure 5. Standby Current Drain

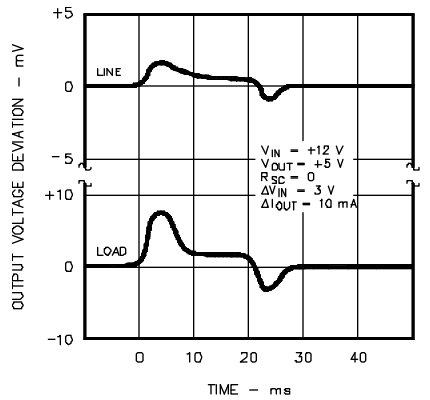

Figure 6. Transient Response

Application Information

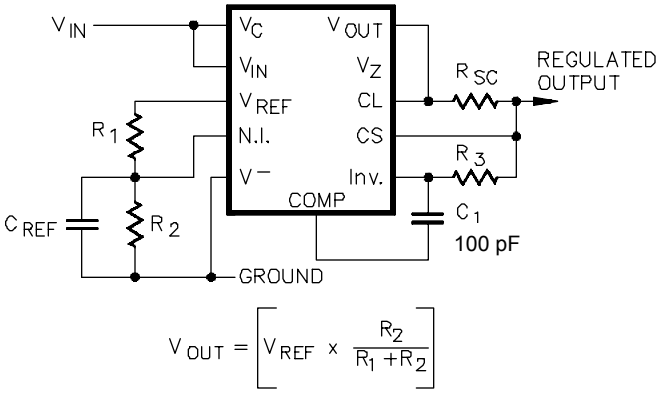

Figure 7 - Basic Low Voltage Regulator V_{OUT} = 2 V TO 7 V

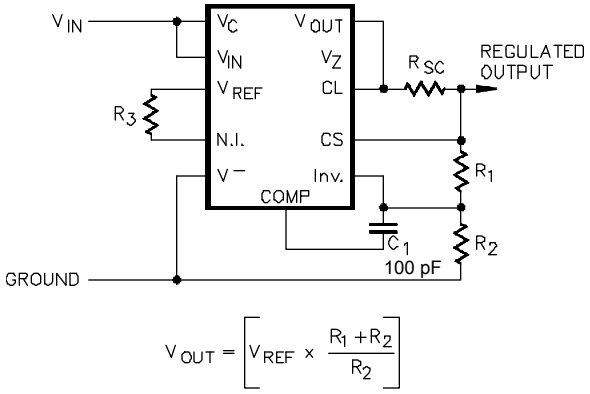

Figure 8 - Basic High Voltage Regulator V_{OUT} = 7 V TO 37 V

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Application Information (Continued)

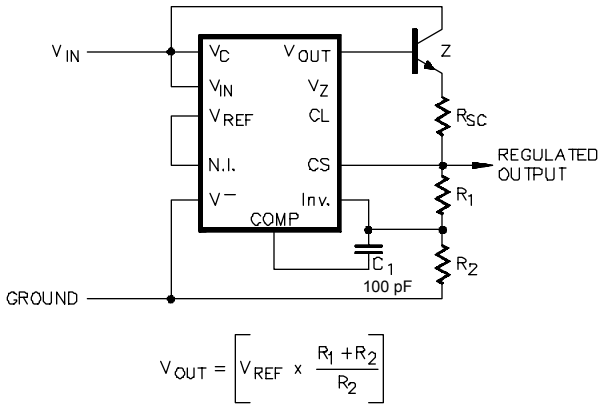


Figure 9 - High Current Regulator External NPN Transistor I_L = 1.0 A

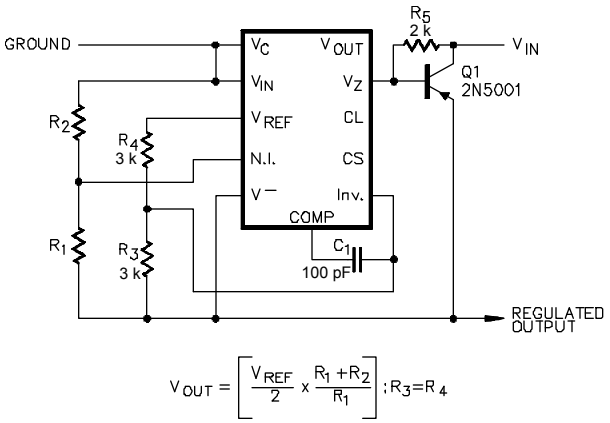
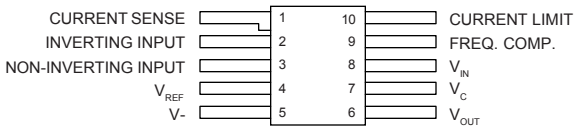
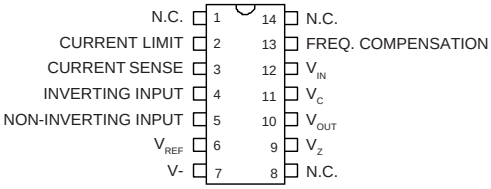
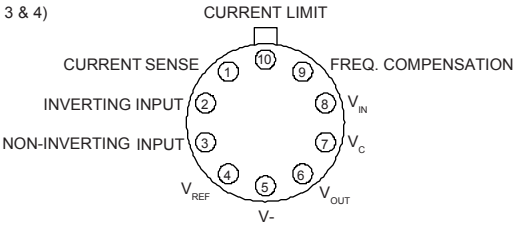


Figure 10 - Negative Voltage Regulator

Connection Diagrams and Ordering Information (See Notes Below)

Package	Part Number	Ambient Temperature Range	Connection Diagram
10-PIN CERAMIC FLAT PACK F - PACKAGE	SG723F-JAN	-55°C to 125°C	(Note 3) 
14-PIN CERAMIC DIP J - PACKAGE	SG723J-JAN	-55°C to 125°C	
10-PIN METAL CAN T - PACKAGE	SG723T-JAN SG723T	-55°C to 125°C -55°C to 125°C	(Notes 3 & 4) 

Note 1. Contact factory for JAN product availablity.
2. All packages are viewed from the top. Lead finish is Sn63/Pb37 for RoHS compliant version contact factory.
3. V_Z output is not available in T, F-packages.
4. Pin 5 is connected to case.

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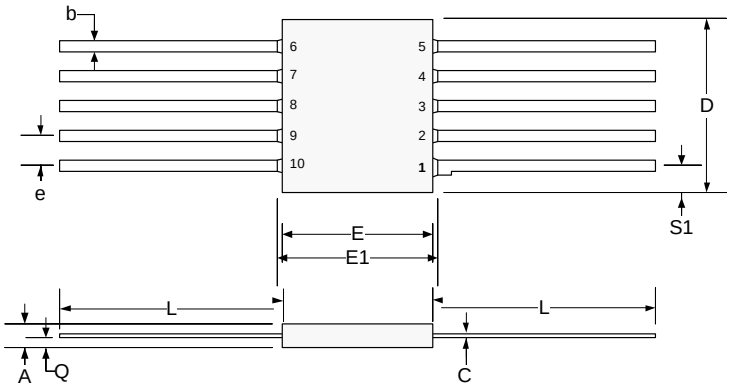
Package Outline Dimensions

Controlling dimensions are in inches, metric equivalents are shown for general information.

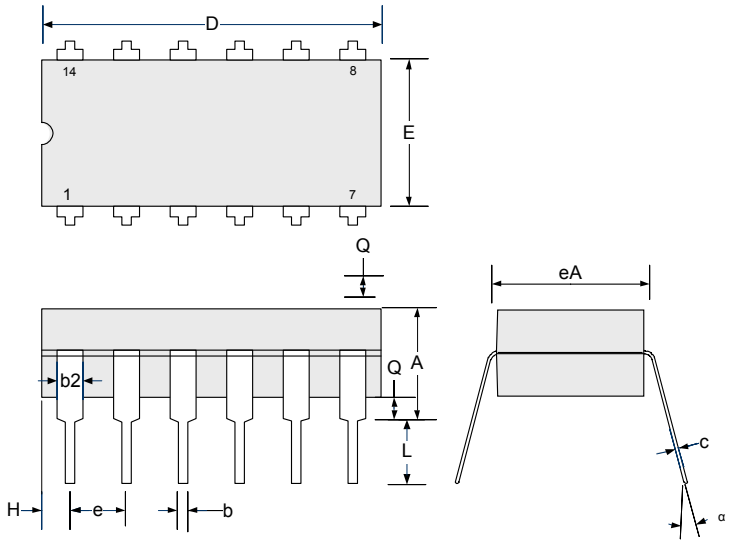


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.45	1.90	0.057	0.075
b	0.25	0.483	0.010	0.019
c	0.102	0.152	0.004	0.006
D	-	7.37	-	0.290
E	6.04	6.40	0.238	0.252
E1	-	6.91	-	0.272
e	1.27 BSC		0.050 BSC	
L	6.35	9.40	0.250	0.370
Q	0.51	1.02	0.020	0.040
S1	0.20	0.38	0.008	0.015

Note:

1. Lead No. 1 is identified by tab on lead or dot on cover.
2. Leads are within 0.13 mm (.0005") radius of the true position (TP) at maximum material condition.
3. Dimension "e" determines a zone within which all body and lead irregularities lie.
4. Dimensions are in mm, inches are for reference only.

Figure 11 · F 10-Pin Ceramic Flat-pack Package Outline Dimensions



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	-	5.08	-	0.200
b	0.38	0.51	0.015	0.020
b2	1.04	1.65	0.045	0.065
c	0.20	0.38	0.008	0.015
D	19.30	19.94	0.760	0.785
E	5.59	7.11	0.220	0.280
e	2.54 BSC		0.100 BSC	
eA	7.37	7.87	0.290	0.310
H	0.63	1.78	0.025	0.070
L	3.18	5.08	0.125	0.200
α	-	15°	-	15°
Q	0.51	1.02	0.020	0.040

Note:

Dimensions do not include protrusions; these shall not exceed 0.155 mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 12 · J 14-Pin Ceramic Dip Package Dimensions

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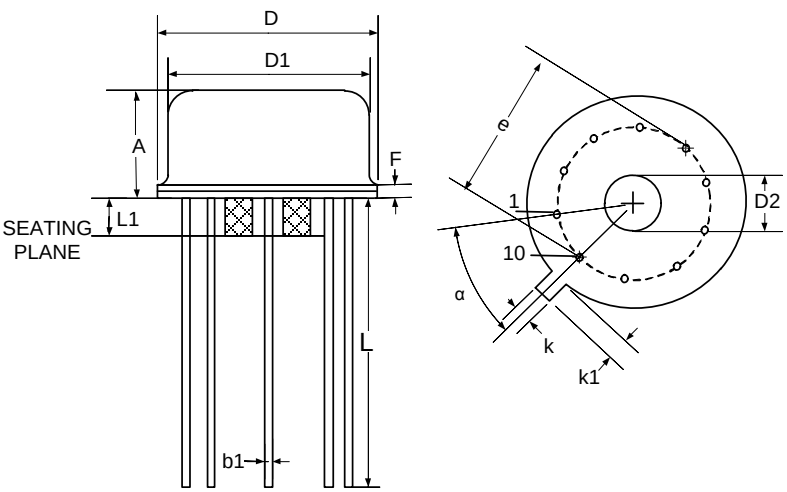
Package Outline Dimensions (Continued)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D	8.890	9.398	0.350	0.370
D1	8.00	8.51	0.315	0.335
A	4.191	4.699	0.165	0.185
b1	0.406	0.533	0.016	0.021
F	-	1.016	-	0.040
e	5.842 TYP		0.230 TYP	
k	0.711	0.864	0.028	0.034
k1	0.737	1.143	0.029	0.045
L	12.70	14.48	0.500	0.570
α	36° TYP		36° TYP	
D2	3.556	4.064	0.140	0.160
L1	0.254	1.016	0.010	0.040

Note:
Dimensions do not include protrusions; these shall not exceed 0.155 mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 13 · T 10-Pin Metal Can Package Dimensions

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